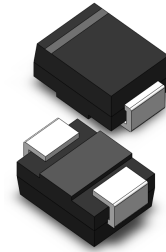


VOLTAGE RANGE: 400V
CURRENT: 1.0 A

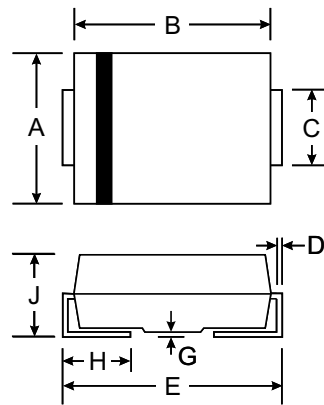


Features

- Miniature Size, Surface Mount Device
- Low Forward Voltage Drop
- High Surge Capability
- Low Power Loss, High Efficiency
- Ultra-Fast Recovery
- Packaged in 12mm Tape and Reel
- Not Rolling During Assembly

Mechanical Data

- Case: SMB/DO-214AA, Molded Plastic
- Terminals: Solder Plated, Solderable per MIL-STD-750, Method 2026
- Polarity: Cathode Band or Cathode Notch
- Marking: Type Number
- Weight: 0.093 grams (approx.)



SMB(DO-214AA)		
Dim	Min	Max
A	3.30	3.94
B	4.06	4.70
C	1.91	2.21
D	0.15	0.31
E	5.00	5.59
G	0.10	0.20
H	0.76	1.52
J	2.00	2.62
All Dimensions in mm		

Maximum Ratings @ T_A = 25°C unless otherwise specified

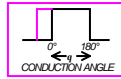
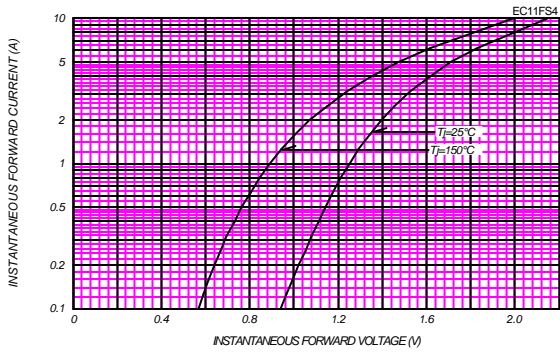
Characteristic	Symbol	EC11FS4	Unit
Repetitive Peak Reverse Voltage	V _{RRM}	400	V
Non-repetitive Peak Reverse Voltage	V _{RSM}	440	V
Average Rectified Forward Current 50Hz Half Sine Wave Resistive Load	I _O	0.76 1.0	A
R.M.S. Forward Current	I _{F(RMS)}	1.57	A
Surge Forward Current 50Hz Half Sine Wave, 1 cycle, Non-repetitive	I _{FSM}	20	A
Operating Junction Temperature Range	T _{jw}	-40 to +150	°C
Storage Temperature Range	T _{stg}	-40 to +150	°C

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Peak Reverse Current T _j = 25 °C, V _{RM} = V _{RRM}	I _{RM}	-	-	20	μA
Peak Forward Voltage T _j = 25 °C, I _{FM} = 0.8A	V _{FM}	-	-	1.25	V
Reverse Recovery Time I _{FM} = 1A, -di/dt = 50A/μs, T _a = 25 °C	t _{rr}	-	-	30	ns
Thermal Resistance Junction to Ambient	R _{th(j-a)}	-	-	157	°C /W
		-	-	108	

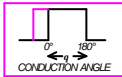
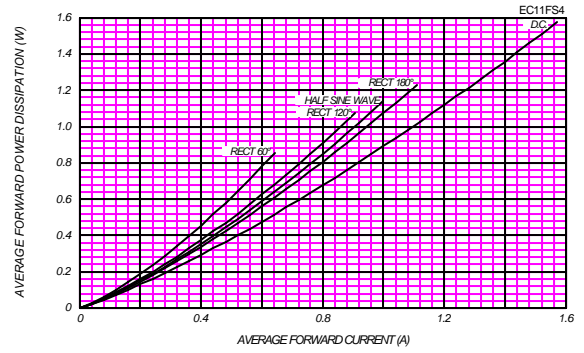
1 Glass Epoxy Substrate Mounted (Soldering Lands=2x2mm, Both Sides)

2 Alumina Substrate Mounted (Soldering Lands=2x2mm, Both Sides)

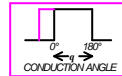
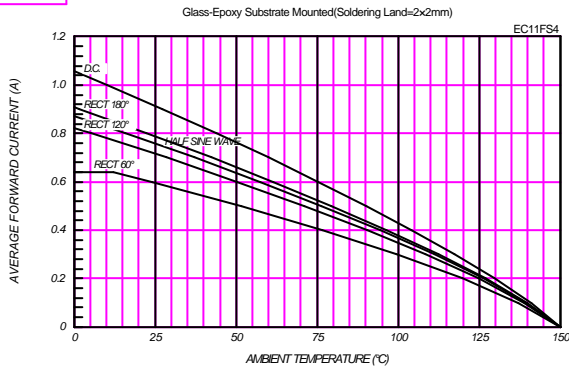
FORWARD CURRENT VS. VOLTAGE



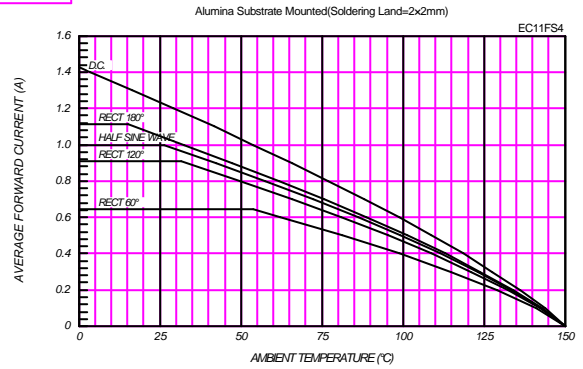
AVERAGE FORWARD POWER DISSIPATION



AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE



AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE



SURGE CURRENT RATINGS

f=50Hz; Half Sine Wave, Non-Repetitive, No Load

